



Material Content Data Sheet



Sales Product Name		BSZ017NE2LS5I		Issued		25. September 2017		
MA#		MA001290992						
Package		PG-TSDSON-8-26		Weight*		35.56 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.393	1.10	1.10	11039	11039
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		102	
	non noble metal	zinc	7440-66-6	0.015	0.04		409	
	non noble metal	iron	7439-89-6	0.291	0.82		8175	
wire	non noble metal	copper	7440-50-8	11.804	33.19	34.06	331942	340628
	non noble metal	copper	7440-50-8	0.013	0.04	0.04	378	378
	encapsulation	organic material	carbon black	1333-86-4	0.036	0.10		1000
	plastics	epoxy resin	-	1.831	5.15		51502	
	inorganic material	silicondioxide	60676-86-0	15.914	44.77	50.02	447516	500018
leadfinish	non noble metal	tin	7440-31-5	0.400	1.13	1.13	11254	11254
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	571	571
solder	noble metal	silver	7440-22-4	0.016	0.04		436	
	non noble metal	tin	7440-31-5	0.012	0.03		349	
	non noble metal	lead	7439-92-1	0.592	1.67	1.74	16658	17443
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		36	
	non noble metal	zinc	7440-66-6	0.005	0.01		142	
	non noble metal	iron	7439-89-6	0.101	0.28		2848	
	non noble metal	copper	7440-50-8	4.112	11.56	11.85	115643	118669
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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